

Day : Saturday  
Date: 7/24/2004


**PALM INTRANET**

Time: 13:47:12

**Inventor Name Search Result**

Your Search was:

Last Name = ONITSUKA

First Name = YASUTO

Application#	Patent#	Status	Date Filed	Title	Inventor Name 9
<u>10697581</u>	Not Issued	030	10/30/2003	BONDING METHOD	ONITSUKA, YASUTO
<u>10635314</u>	Not Issued	020	08/06/2003	TRANSFER CARRIER FOR FLEXIBLE PRINTED CIRCUIT BOARD AND ELECTRONIC PARTS MOUNTING METHOD TO FLEXIBLE PRINTED CIRCUIT BOARD	ONITSUKA, YASUTO
<u>09877112</u>	6618937	150	06/11/2001	A METHOD OF ASSEMBLING ELECTRONIC APPLICATIONS AND DISPLAY DEVICES	ONITSUKA, YASUTO
<u>08718974</u>	5839645	150	09/26/1996	BONDING MACHINE OF ELECTRONIC COMPONENTS AND BONDING METHOD THEREOF	ONITSUKA, YASUTO
<u>08429871</u>	5628660	150	04/27/1995	BONDING APPARATUS AND BONDING METHOD OF DEVICES	ONITSUKA, YASUTO
<u>08341095</u>	5513792	150	11/17/1994	BONDING APPARATUS	ONITSUKA, YASUTO
<u>08338413</u>	5591295	150	11/14/1994	BONDING APPARATUS FOR ELECTRONIC COMPONENTS	ONITSUKA, YASUTO
<u>08313595</u>	5501005	150	09/29/1994	MOUNTING DEVICE OF ELECTRONIC COMPONENTS AND A MOUNTING METHOD	ONITSUKA, YASUTO
<u>08299766</u>	5501004	150	09/01/1994	OUTER-LEAD BONDING APPARATUS AND METHOD THEREFOR	ONITSUKA, YASUTO

Inventor Search Completed: No Records to Display.

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	Last Name	First Name	
<b>Search Another: Inventor</b>	<input type="text" value="ONITSUKA"/>	<input type="text" value="YASUTO"/>	<input type="button" value="Search"/>

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L Number	Hits	Search Text	DB	Time stamp
1	88	((press or pressure) near4 (bond or bonding or bonder)) and (detect or detecting) and (position or positioning) and (29/\$.ccls.) and (tape or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 14:04
2	1	((press or pressure) near4 (bond or bonding or bonder)) and (optical near2 camera) and (position or positioning) and (29/\$.ccls.) and (tape or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 13:50
3	0	((press or pressure) near4 (bond or bonding or bonder)) and (optical near2 camera) and (position or positioning) and (156/\$.ccls.) and (tape or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 13:50
4	0	((press or pressure) near4 (bond or bonding or bonder)) and (optical near2 camera) and ("XY" near4 table) and (156/\$.ccls.) and (tape or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 13:51
5	0	((press or pressure) near4 (bond or bonding or bonder)) and (optical near2 camera) and ("XY" near4 table) and (29/\$.ccls.) and (tape or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 13:51
6	0	((press or pressure) near4 (bond or bonding or bonder)) and (optical near2 camera) and ("X Y" near4 table) and (29/\$.ccls.) and (tape or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 13:51
7	0	((press or pressure) near4 (bond or bonding or bonder)) and (optical near2 camera) and ("X Y" near4 table) and (156/\$.ccls.) and (tape or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 13:51
9	1	((press or pressure) near4 (bond or bonding or bonder)) and (optical near2 camera) and ("X Y") and (29/\$.ccls.) and (tape or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 13:51
8	1	((press or pressure) near4 (bond or bonding or bonder)) and (optical near2 camera) and ("X Y") and (156/\$.ccls.) and (tape or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 14:04
10	2	((head) near4 (bond or bonding or bonder)) and (optical near2 camera) and ("X Y") and (156/\$.ccls.) and (tape or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 14:04
11	8	((head) near4 (bond or bonding or bonder)) and (optical near2 camera) and ("X Y") and (29/\$.ccls.) and (tape or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 14:04
12	79	((head) near4 (bond or bonding or bonder)) and (detect or detecting) and (position or positioning) and (29/\$.ccls.) and (tape or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 14:04

13	39	((head) near4 (bond or bonding or bonder)) and (detect or detecting) and (position or positioning) and (156/\$.ccls.) and (tape or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 14:05
-	879	(ACF or anisotropic) and (tape or film) and (156/\$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 19:08
-	1	("20040129364").PN.	US-PGPUB	2004/07/23 16:54
-	1207	(156/64).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/22 21:13
-	2	("6596115").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/22 13:14
-	1	("6544377").PN.	USPAT	2004/07/22 13:22
-	2225	(29/832).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/22 21:13
-	403	(29/833).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/22 21:13
-	461	(29/834).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/22 21:13
-	283	(29/738).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/22 21:13
-	1985	(29/739).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/22 21:13
-	198	(156/539).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 18:34
-	104	(29/836).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/22 21:26
-	514	(156/538).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 15:12
-	0	2003-59975	JPO	2004/07/23 15:12
-	0	"59975"	JPO	2004/07/23 15:12

-	10	yasuto.in. near3 onitsuka.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 15:24
-	1244	(29/740).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 15:25
-	0	yasuto.in. and onitsuka.in.	JPO	2004/07/23 15:25
-	0	yasuto and onitsuka	JPO	2004/07/23 15:25
-	0	6618937.URPN.	USPAT	2004/07/23 16:45
-	5	("5495661"   "5727311"   "5894657"   "6086641"   "6140707").PN.	USPAT	2004/07/23 16:45
-	1	("20010032030").PN.		
-	364	(156/358).CCLS.	US-PGPUB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 16:54 2004/07/23 18:34
-	214	(156/360).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 18:34
-	815	(156/361).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 18:34
-	288	(156/362).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 19:06
-	826	(156/297).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 19:06
-	623	(156/299).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 19:06
-	414	(156/300).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 19:06
-	1041	(ACF or anisotropic) and (tape or film) and (29/\$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 19:08
-	6	(plural near2 board) and (detect or detecting) and (position or positioning) and (156/\$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 21:09

-	10	(plural near2 board) and (detect or detecting) and (position or positioning) and (29/\$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 19:12
-	228	((press or pressure) near4 (bond or bonding or bonder)) and (detect or detecting) and (position or positioning) and (156/\$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 21:10
-	139	((press or pressure) near4 (bond or bonding or bonder)) and (detect or detecting) and (position or positioning) and (29/\$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 21:10
-	102	((press or pressure) near4 (bond or bonding or bonder)) and (detect or detecting) and (position or positioning) and (156/\$.ccls.) and (tape or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 21:10